Product Document

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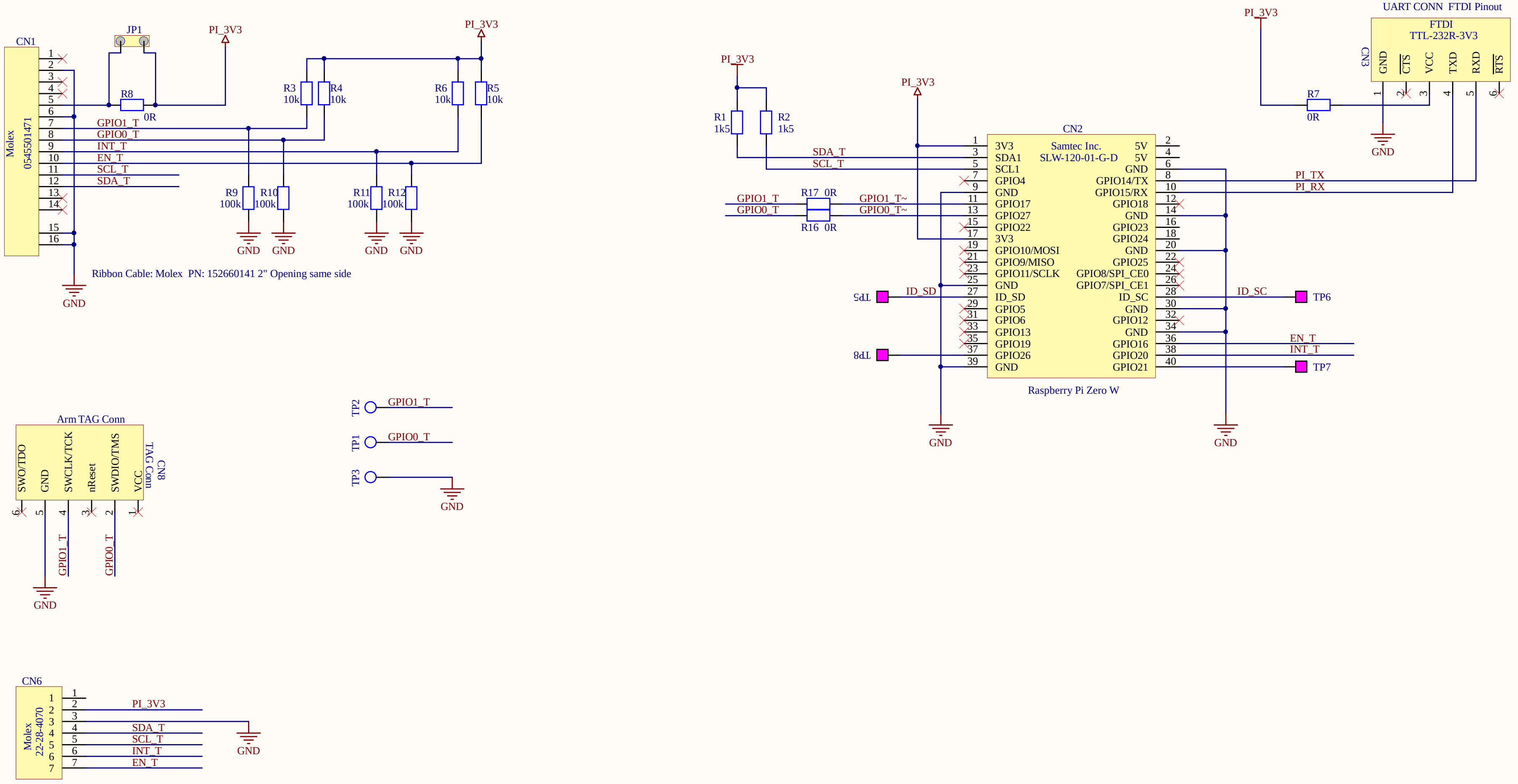
TOF Linux Interface Board

Linux Interface board for TOF

Revision History

Revision: A K. Weiner
Initial release

Title: TOF Linux Interface Board
Board Number: EVM-TOFDEMO-04
Rev: A
Date: 14.01.2019
Author: J.Dolic
Sheet 2 of 7



Title: **TOF Linux Interface Board**

Board Number: EVM-TOFDEMO-04

Rev: A

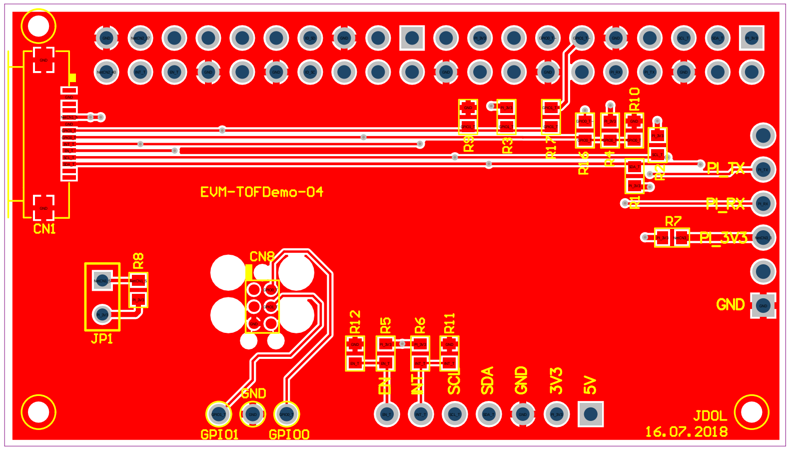
Date: 14.01.2019

Author: J.Dolic

Sheet 3 of 3

Board Details

1. Board Size: 2200mils x 1200mils
2. Board Thickness: 62mils
3. Component count: 27
4. Pad Count: 122
5. Hole Count: 88
6. Soldermask Color: Green
7. Silkscreen Color: White
8. No Silkscreen over exposed copper.
9. Dimensions shown are in mils.
10. Boards Shall be fabricated to IPC-600 Class 1
11. The board Material shall be: FR-4
12. The PCB assembly shall be ROHS compliant.



Layers Currently On

Title Block
TOP

Board Outline

Top Overlay

Multi-Layer

Title TOF Linux Interface Board
Number EVM-TOFDEMO-04
Rev A
Print Name Top Layer
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By:J.Dolic

Board Details

1. Board Size: 2200mils x 1200mils
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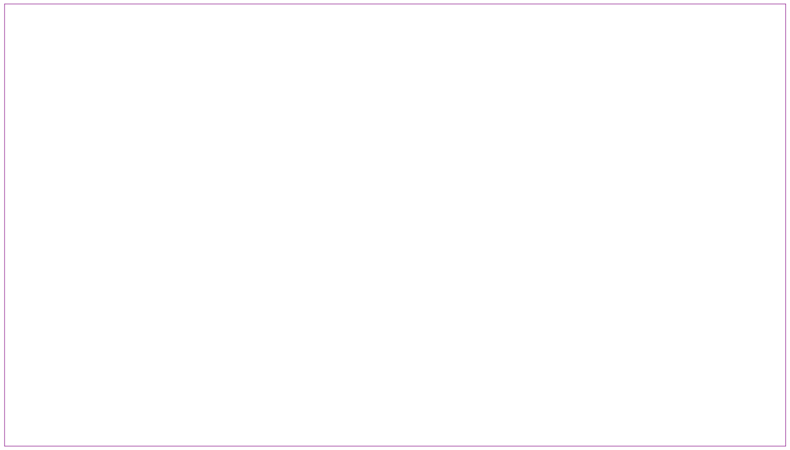

Layers Currently On

Title Block **Board Outline**	Multi-Layer

Title TOF Linux Interface Board
Number EVM-TOFDEMO-04
Rev A
Print Name
Mid1 Layer - GND
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By:J.Dolic

Board Details

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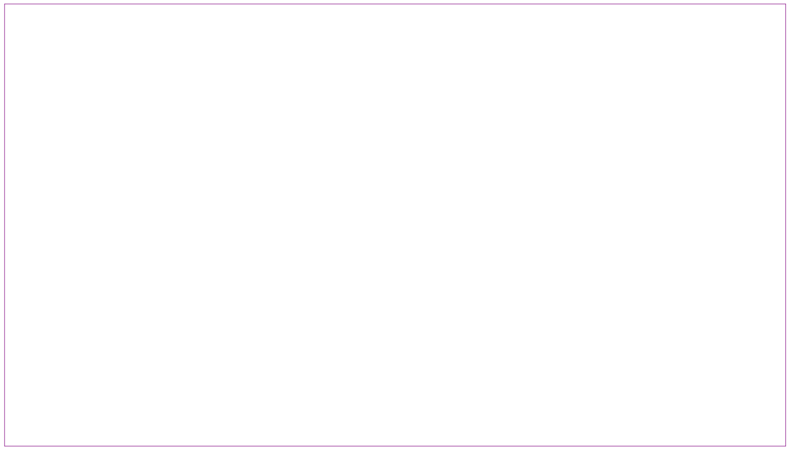

Layers Currently On

Title Block
Board Outline
Multi-Layer

Title TOF Linux Interface Board
Number EVM-TOFDEMO-04
Rev A
Print Name
Mid2 Layer - PWR
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By:J.Dolic

Board Details

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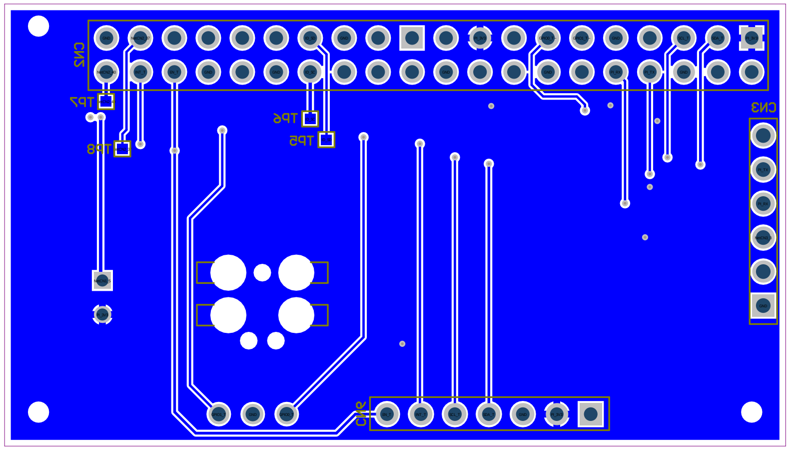

Layers Currently On

Title Block	
BOTTOM	
Board Outline	**Bottom Overlay**
	Multi-Layer

Title TOF Linux Interface Board
Number EVM-TOFDEMO-04
Rev A
Print Name
Bottom Layer
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By:J.Dolic

Board Details

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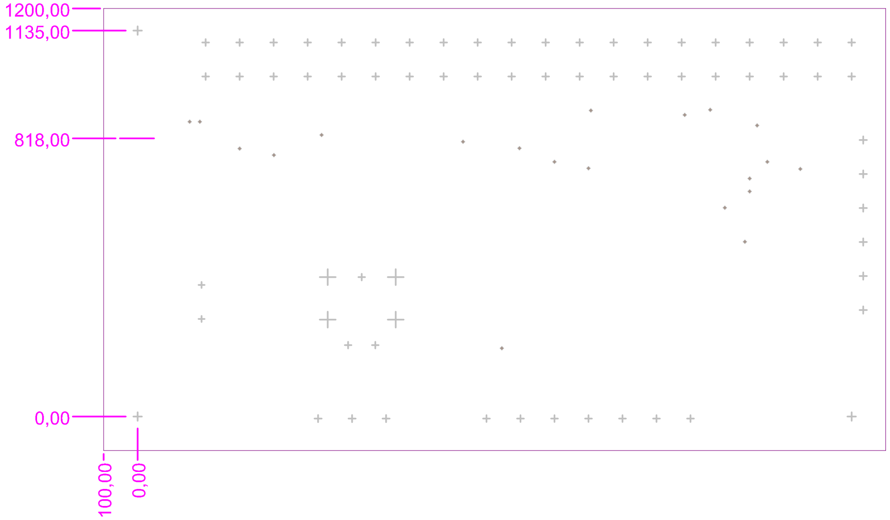

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				▨
2	Top Solder	Solder Resist	0,40mil	3,5	▨
3	TOP	Copper	1,20mil		▨
4	Dielectric1	FR-4	9,00mil	4,5	▨
5	BOTTOM	Copper	1,20mil		▨
6	Bottom Solder	Solder Resist	0,40mil	3,5	▨
7	Bottom Overlay				▨

Layers Currently On

Title Block

Dimension
Board Outline

Drill Guide

Keep-Out Layer
Multi-Layer

Title TOF Linux Interface Board
Number EVM-TOFDEMO-04
Rev A
Print Name
Board Dimensions
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By:J.Dolic

Board Details

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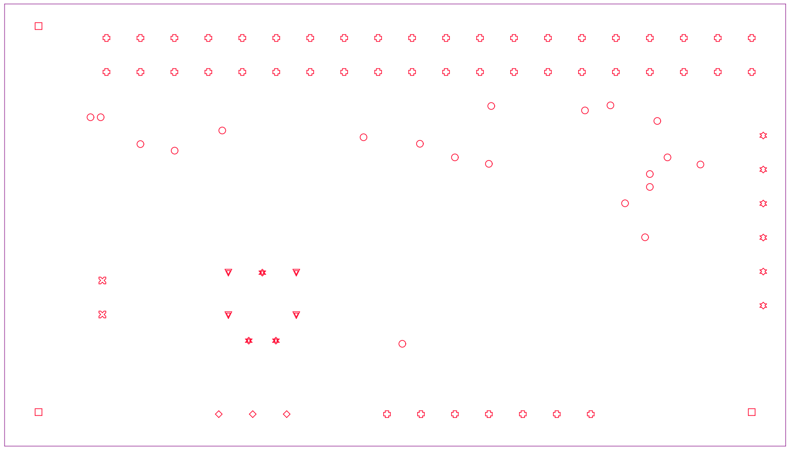

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
⌘	2	35,43mil (0,900mm)	PTH	Round	TOP - BOTTOM	Pad	(Mixed)
✶	3	39,02mil (0,991mm)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
◇	3	42,00mil (1,067mm)	PTH	Round	TOP - BOTTOM	Pad	Rounded
□	3	50,00mil (1,270mm)	NPTH	Round	TOP - BOTTOM	Pad	Rounded Rectangle
▽	4	93,50mil (2,375mm)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
✡	6	43,00mil (1,092mm)	PTH	Round	TOP - BOTTOM	Pad	(Mixed)
○	20	8,00mil (0,203mm)	PTH	Round	TOP - BOTTOM	Via	Rounded
✙	47	40,00mil (1,016mm)	PTH	Round	TOP - BOTTOM	Pad	(Mixed)
	88 Total						

Layers Currently On

Title Block	
	Drill Drawing
Board Outline	

Title TOF Linux Interface Board
Number EVM-TOFDEMO-04
Rev A
Print Name
Drill Drawing
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By:J.Dolic

Board Details

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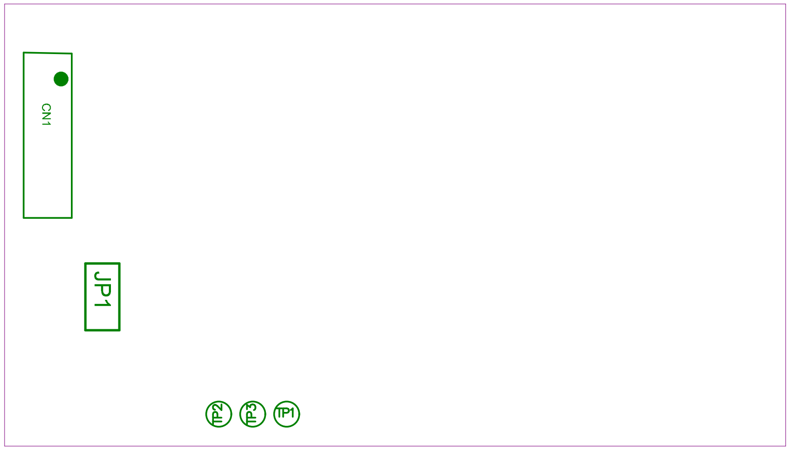

Layers Currently On

Title Block

Board Outline
Assembly Top

Multi-Layer

Title TOF Linux Interface Board
Number EVM-TOFDEMO-04
Rev A
Print Name TOP Assembly
Variant: Default Build
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By:J.Dolic

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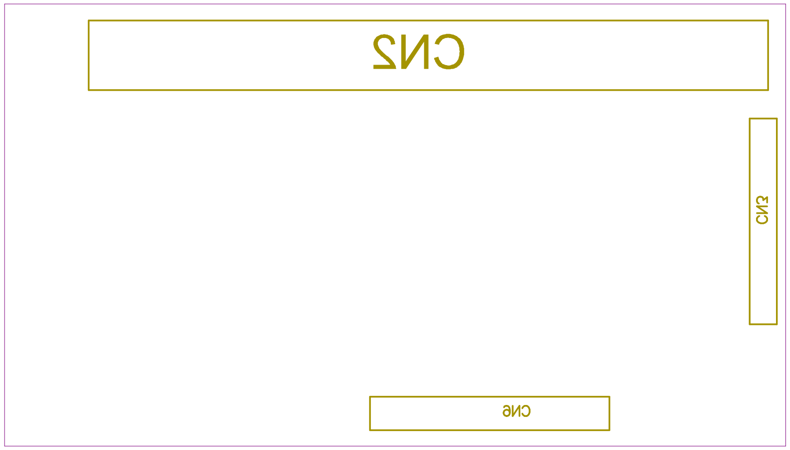

Layers Currently On

Title Block	
Board Outline	
Assembly Bottom	**Multi-Layer**

Title	TOF Linux Interface Board
Number	EVM-TOFDEMO-04
Rev	A
Print Name	BOTTOM Assembly Mirrored
Variant: Default Build	Print Date: 14.01.2019
File: PCB.PcbDoc	Drawn By:J.Dolic

Design Rules Verification Report

Filename : \\fsup04\cnc_prodmgmt\OSL\11_HW_Application_PS\Koloth\Hardware\EVM-TOFD

Warnings 0
Rule Violations 0

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=6mil) (All),(All)	0
Short-Circuit Constraint (Allowed=Yes) (IsTextInverted),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Width Constraint (Min=4.921mil) (Max=393.701mil) (Preferred=11.811mil) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=15.748mil) (Conductor Width=5.906mil) (Air Gap=5.906mil)	0
Minimum Annular Ring (Minimum=5mil) (All)	0
Hole Size Constraint (Min=8mil) (Max=1000mil) (All)	0
Hole To Hole Clearance (Gap=11.811mil) (All),(All)	0
Minimum Solder Mask Sliver (Gap=1mil) (All),(All)	0
Silk To Solder Mask (Clearance=0mil) (IsPad),(All)	0
Silk to Silk (Clearance=0mil) (All),(All)	0
Net Antennae (Tolerance=0mil) (All)	0
Height Constraint (Min=0mil) (Max=1000mil) (Prefered=500mil) (All)	0
Total	0

Electrical Rules Check Report

Class	Document	Message
		Successful Compile for EVM-TOFDemo-04.PrjPcb

Designator	Comment	Description	Quantity	Manufacturer	Manufacturer Part Number
CN1	CONN FFC TOP 14POS 0.50MM R/A	CONN FFC TOP 14POS 0.50MM R/A	1	Molex	0545501471
R1, R2	1k5	MULTICOMP MC0063W060351K5 Surface Mount Chip Resistor, Thick Film, MC Series, 1.5 kohm, 63 mW, 5%, 50 V, 0603 [1608 Metric]	2	Multicomp	MC0.063W06035%1K5
R8	0R	MULTICOMP MC0063W06030R Chip SMD Resistor, MC Series, 0.063 W, 50 V, 0603 [1608 Metric]	1	Multicomp	MC0.063W06030R